# Chip Scale Review

## 2019 Editorial Calendar

### January • February

*(Editorial close date: 12/1/2018*

| Topics | Industry Events |
|---|---|
| 5G developments<br>Stretchable interconnects<br>Low-temp direct bond interconnect<br>Thermal debonding and warpage in FOWLP<br>Transfer molding for FOWLP<br>TSV and RDL technologies<br>3D IC metrology<br>Discontinuities drive data integration<br>Innovative materials & processes<br>Next-gen large die WLCSP structure | • **APEX Expo** San Diego, CA (Jan 26-31)<br>• **3D & Systems Summit** Dresden, Germany (Jan 28-30)<br>• **SMTA Pan Pac Microelectronics Symposium** Kauai, Hawaii (Feb 11-14)<br>• **FLEX / MEMS & Sensors Technical Congress** Monterey, CA (Feb 18-21) |

***Ad Space Close Jan 18 - Ad Materials Close Jan 25***

### March • April

*(Editorial close date: 1/15/19)*

| Topics | Industry Events |
|---|---|
| SiP technology, drivers & market trends<br>3D system packaging<br>Thin wafer handling<br>High yield solutions for FOWLP<br>Solders in semiconductor device assembly<br>Hi-reliability standards<br>MEMS sensors<br>Innovative microelectronic solutions<br>OSAT new & emerging package offerings | • **TestConX** Mesa, AZ (March 3-6)<br>• **IMAPS Device Packaging** Fountain Hills, AZ (March 4-7)<br>• **SEMICON China** Shanghai, China (March 20-22)<br>• **ISS Europe** Milan, Italy (March 31-April 2**)** |

***Ad Space Close Mar 13 - Materials Close Mar 22***

### May • June

*(Editorial close date: 3/8)*

| Topics | Industry Events |
|---|---|
| AI in packaging<br>Heterogeneous integration<br>Multi-die/ substrate heterogeneous packages<br>Reliability<br>Automotive<br>Inspection for advanced packaging processes<br>RF, Final test<br>Advances in wafer probe<br>Smart devices and applications | • **SEMICON SE Asia** Kuala Lumpur, Malaysia (May 7-9)<br>• **ECTC** Las Vegas, NV (May 28-31)<br>• **IEEE/SW Test Workshop (SWTW)** San Diego, CA (June 2-5 )<br>• **Sensors Expo** San Jose, CA (June 25-27)<br>• **SEMICON West** San Francisco, CA (July 9-11) |

***Ad Space Close May 8 - Ad Materials Close May 17***

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*Notes: Editorial calendar topics and distribution are subject to change without notice and are contingent on logistics and magazine production.*

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